Method For Producing A Wafer Provided With Chips

Abstract

The present invention relates to a method for producing a product wafer (1) equipped with chips (12, 15) on two sides, in particular, comprising the following sequence: - processing a first side (3) of the product wafer - bonding the product wafer by the first side thereof on a first, rigid carrier wafer (8) with a first intermediate layer (18) consisting of a first adhesion layer (6) applied at least marginally - processing a second side of the product wafer, said second side lying opposite the first side, and - bonding the product wafer by the second side thereof on a second, rigid carrier wafer (13) with a second intermediate layer (17) consisting of a second adhesion layer (14) applied at least marginally, wherein the first intermediate layer and the second intermediate layer are embodied differently such that the first carrier wafer (8) can be separated from the product wafer selectively before the second carrier wafer (13).

Figure 7